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Sommario/riassunto	"This book focuses on modern technology and how electronic packaging plays a major role in moving technology forward. With the enhancement of mobile technology and its challenges, the need for packing technology solutions is evident. The first part of the book gives an overview of electronic packaging and provides the reader with the fundamentals of the most important packaging techniques such as wire bonding, tap automatic bonding, flip chip solder joint bonding, microbump bonding, and low temperature direct Cu-to-Cu bonding. Part two consists of concepts of electronic circuit design and its role in low power devices, biomedical devices, and circuit integration. The last part of the book contains topics based on the science of electronic packaging and the reliability of packaging technology"--